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Mark Frimann
SC Product Stewardship
Management
SC Quality – Texas
Instruments

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<th><a href="http://www.ti.com/automotive">www.ti.com/automotive</a></th>
</tr>
</thead>
<tbody>
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</tr>
<tr>
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</tr>
<tr>
<td>Interface</td>
<td>interface.ti.com</td>
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<td><a href="http://www.ti.com/medical">www.ti.com/medical</a></td>
</tr>
<tr>
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<td>Security</td>
<td><a href="http://www.ti.com/security">www.ti.com/security</a></td>
</tr>
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<td>Power Mgmt</td>
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</tr>
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</tr>
<tr>
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<td></td>
</tr>
<tr>
<td>OMAP Applications Processors</td>
<td><a href="http://www.ti.com">www.ti.com</a> omap</td>
<td>TI E2E Community</td>
<td>e2e.ti.com</td>
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<tr>
<td>Wireless Connectivity</td>
<td><a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a></td>
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